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IWASAKI et al.(10) **Pub. No.: US 2023/0232538 A1**(43) **Pub. Date: Jul. 20, 2023**(54) **SUBSTRATE FOR PRINTED WIRING
BOARD AND MULTILAYER SUBSTRATE**(30) **Foreign Application Priority Data**

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Koka-shi, Shiga (JP)(57) **ABSTRACT**

A substrate for a printed wiring board includes a base layer, and a copper foil directly or indirectly stacked on at least a part of one or both surfaces of the base layer. The base layer includes a matrix containing a fluororesin as a main component and one or more reinforcing material layers included in the matrix, and a ratio B/A is 0.003 to 0.37, where A is an average thickness of the base layer, and B is an average distance between a surface of the copper foil facing the matrix and a surface of a reinforcing material layer closest to the surface of the copper foil facing the copper foil.

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